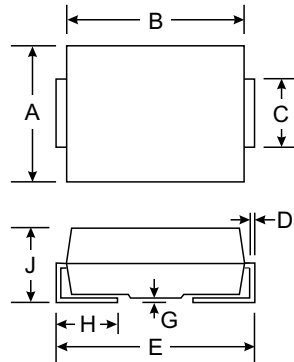


Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 100A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Plastic Material - UL Flammability Classification 94V-0



	SMA		SMB		SMC	
Dim	Min	Max	Min	Max	Min	Max
A	2.29	2.92	3.30	3.94	5.59	6.22
B	4.00	4.60	4.06	4.57	6.60	7.11
C	1.27	1.63	1.96	2.21	2.75	3.18
D	0.15	0.31	0.15	0.31	0.15	0.31
E	4.80	5.59	5.00	5.59	7.75	8.13
G	0.10	0.20	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52	0.76	1.52
J	2.01	2.62	2.00	2.62	2.00	2.62
All Dimensions in mm						

Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Approx. Weight: SMA 0.064 grams
SMB 0.093 grams
SMC 0.21 grams
- Marking: Type Number

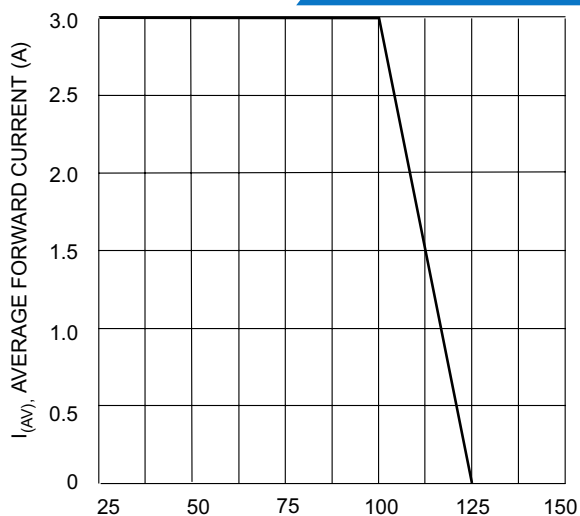
"A" Suffix Designates SMA Package
"B" Suffix Designates SMB Package
No Suffix Designates SMC Package

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

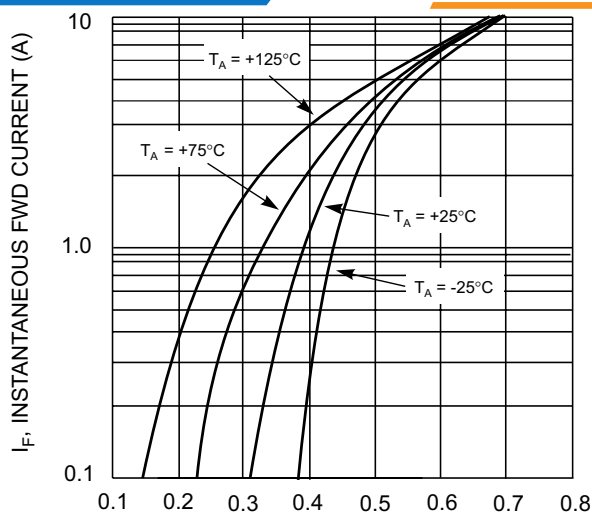
Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	B320/A/B	B330/A/B	B340/A/B	B350/A/B	B360/A/B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	50	60	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	V
Average Rectified Output Current @ $T_T = 100^{\circ}\text{C}$	I_O	3.0					A
Non-Repetitive Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100					A
Forward Voltage @ $I_F = 3.0\text{A}$	V_{FM}	0.50			0.70		V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ at Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	I_{RM}	0.5 20					mA
Typical Junction Capacitance (Note 2)	C_j	250					pF
Typical Thermal Resistance, Junction to Terminal (Note 1)	$R_{\theta JT}$	10					$^{\circ}\text{C/W}$
Typical Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	50					$^{\circ}\text{C/W}$
Operating Temperature Range	T_{STG}	-55 to +150					$^{\circ}\text{C}$
Storage Temperature Range	T_j	-55 to +125					$^{\circ}\text{C}$

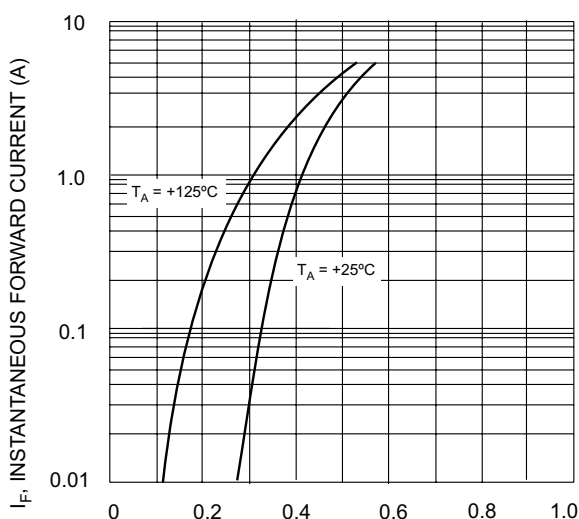
Notes: 1. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pad as heat sink.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.



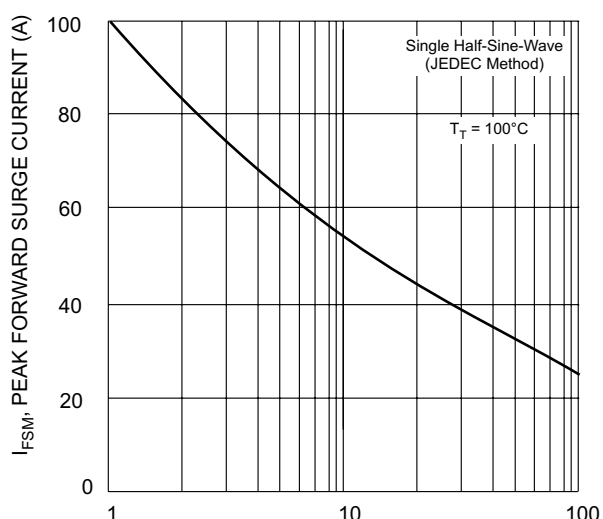
T_T , TERMINAL TEMPERATURE ($^{\circ}\text{C}$)
Fig. 1 Forward Current Derating Curve



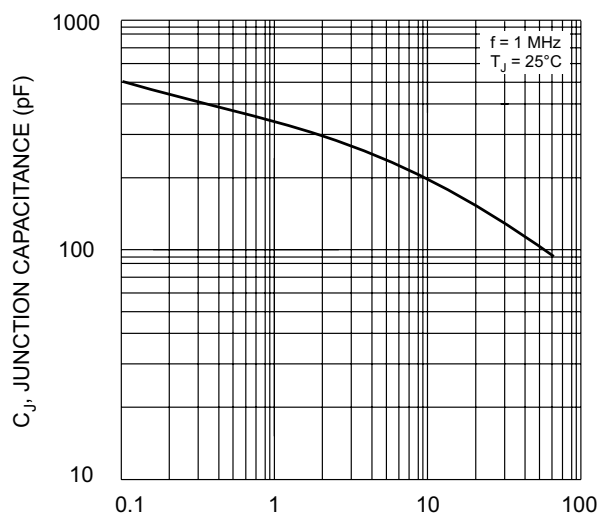
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics - B320/A/B thru B340/A/B



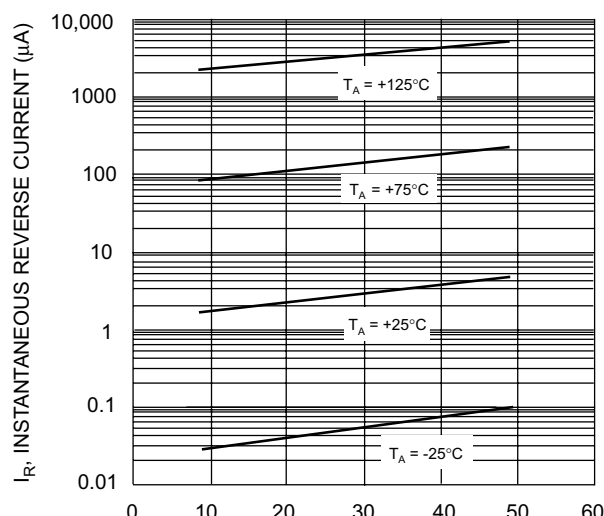
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 3 Typ. Forward Characteristics - B350/A/B thru B360/A/B



NUMBER OF CYCLES AT 60 Hz
Fig. 4 Max Non-Repetitive Peak Fwd Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 5 Typical Junction Capacitance



V_R , INSTANTANEOUS REVERSE VOLTAGE (V)
Fig. 6 Typical Reverse Characteristics, B320/A/B thru B340/A/B

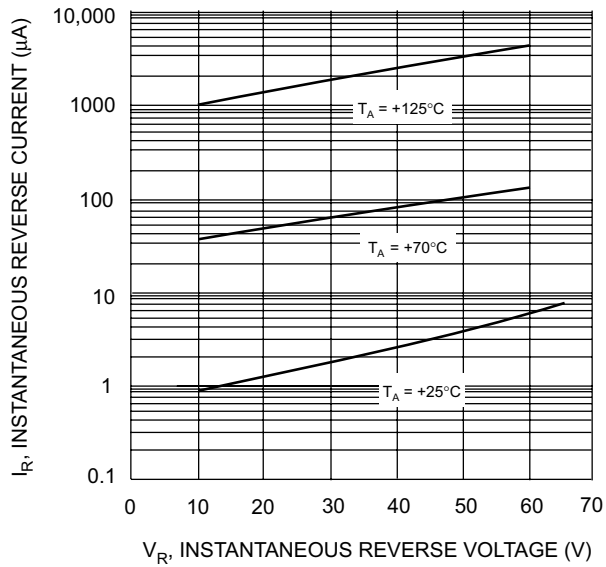


Fig. 7 Typical Reverse Characteristics, B350/A/B thru B360/A/B